Tapes Adwill series

Adwill will give you the Advantage

E series

UV Curable Back-Grinding Tape

The Adwill E-Series of UV curable back-grinding tapes prevents damage on the wafer surface during back-grinding and contamination caused by grinding fluid and/or debris. Adhesion of E-Series back-grinding tapes is substantially decreased by UV irradiation after grinding, allowing easy peeling without stress on the wafer. This feature makes the series suitable for the processing of thin wafers.

Process	Application	Base Material	Tape Name
Back-Grinding	Standard Grinding (wafer thickness after grinding >75 µm)	PO	E-6142S(S) / E-6142A(S)
	Standard Grinding (wafer thickness after grinding >40 µm)	Special Elastomer	E-8180HR
	Micro Bump (including ink dot)	PO	E-6142A(S) / E-6152B
	Medium Bump (height <100 µm)	PO	E-4230BS
		Special Elastomer	E-8310LS342F / E-8280
	High Bump (height <200 µm)	Special Elastomer	E-9481G-A / E-9486 / E-9487
	Antistatic	PO	E-6130AS
	Compound Semiconductor (SiC, GaN, etc.)	PET Composite	E-3190U
		PO	E-4230BS
		Special Elastomer	E-9486 / E-9487 / E-8280
DBG (Dicing Before Grinding)	Standard		E-3000 series
	Flat structure	PET Composite	E-3100UN / E-3090V / E-3090VAS / E-3100V
SDBG (Stealth Dicing Before Grinding)	Medium Bump (height <20 µm)	PET Composite	E-3165KL
	High Bump (height <60 µm)	PET Composite	E-3190U / E-3281B